:	Application No.	Applicant(s)	
Motion of All	10/614,069		
Notice of Allowability	Examiner	BEROZ, MASUD Art Unit	
<u> </u>	David Nhu	2818	
The MAILING DATE of this communication and All claims being allowable, PROSECUTION ON THE MERITS herewith (or previously mailed), a Notice of Allowance (PTOL-INOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT of the Office or upon petition by the applicant. See 37 CFR 1.3	85) or other appropriate commu	n this application. If not inclu	ıded
2. The allowed claim(s) is/are <u>1-24</u> .	•		
•			
3. The drawings filed on <u>03 July 2003</u> are accepted by the			
 4. ☐ Acknowledgment is made of a claim for foreign priority a) ☐ All b) ☐ Some* c) ☐ None of the: 1. ☐ Certified copies of the priority documents hat 2. ☐ Certified copies of the priority documents hat 	ve been received.		
o. Li Copies of the certified copies of the priority of	documents have been received	in this national stage applie	ation from the
international bureau (PCT Rule 17.2(a)).	· · · · · · · · · · · · · · · · · · ·	m this hational stage applica	ation from the
* Certified copies not received:			
Applicant has THREE MONTHS FROM THE "MAILING DATE noted below. Failure to timely comply will result in ABANDON THIS THREE-MONTH PERIOD IS NOT EXTENDABLE. 5. A SUBSTITUTE OATH OR DECLARATION must be subjusted in the subjusted of the subjusted	mitted Nata that the transfer of the second		
was the true to th	ves reason(s) why the path or o	MINER'S AMENDMENT or N declaration is deficient.	NOTICE OF
6. CORRECTED DRAWINGS (as "replacement sheets") mu	ust be submitted.		
(a) including changes required by the Notice of Draftsper	rson's Patent Drawing Review	(PTO-948) attached	
1) ☐ hereto or 2) ☐ to Paper No./Mail Date (b) ☐ including changes required by the attached Examined Paper No./Mail Date Paper No./Mail Date	 r's Amendment / Comment or in	n the Office action of	
r aper rec./iviali Date			
Identifying indicia such as the application number (see 37 CFR each sheet. Replacement sheet(s) should be labeled as such in	The regard according to 31 CFR	1.121(0).	
Z. DEPOSIT OF and/or INFORMATION about the deposit attached Examiner's comment regarding REQUIREMENT	seit of BIOLOGICAL AAA		Note the
ttachment(s)			
Notice of References Cited (PTO-892)		mal Patent Application (PTC	D-152)
Notice of Draftperson's Patent Drawing Review (PTO-948)	6. ☐ Interview Sum	mary (PTO-413),	
☐ Information Disclosure Statements (PTO-1449 or PTO/SB/0 Paper No./Mail Date	08), 7. ☐ Examiner's Ar	ail Date nendment/Comment	
Examiner's Comment Regarding Requirement for Deposit	8. ⊠ Examiner's St	atement of Reasons for Allov	Wones
of Biological Material	9.	and the additional of Allow	wance
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REASONS FOR ALLOWANCE

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1. Claims 1-24 are allowed.

2. The following is an examiner's statement of reasons for allowance: None of the references of record teaches or suggests as cited in claims 1, 15, 22: adhering a dielectric layer to said plurality of microelectronic elements; separating a potion of said dielectric layer from a remaining portion of said dielectric layer along at least one line extending two of said plurality of microelectronic elements; removing the separated portion of said dielectric layer and at least one of said plurality of microelectronic elements adhered to said separated portion of said dielectric layer (as cited in claim 1); juxtaposing a plurality of microelectronic elements with the first major face of said dielectric layer; assembling said microelectronic elements with said dielectric layer by abutting said microelectronic elements against the first adhesive of said dielectric layer; at least partially serving said dielectric layer while maintaining the protective liner as a single piece of material so as to form a plurality of individual microelectronic units overlying said protective liner, wherein each said individual microelectronic unit includes at least one partially served potion of said dielectric layer (as cited in claim 15); juxtaposing a plurality of microelectronic elements with the first major face of said dielectric laver: assembling said microelectronic elements with said dielectric layer by abutting said microelectronic elements against the first adhesive of said dielectric layer; maintaining the protective liner as a single piece of material while dicing said wafer and at least partially severing said dielectric layer for forming a plurality of individual; microelectronic units overlying said protective liner, wherein each said individual microelectronic unit includes at least one of

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said microelectronic chips attached to an at least partially served portion of said dielectric layer

(as cited in claim 22).

3. Any comments considered necessary by applicant must be submitted no later than the

payment of the issue fee and, to avoid processing delays, should preferably accompany the

issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons

for Allowance."

Conclusion

4. The prior art made of record and not relied upon is considered pertinent to applicant's

disclosure: DiStefano et al (5,518,964): Microelectronic Mounting with Multiple Lead

Deformation and Bonding.

5. Any inquiry concerning this communication on earlier communications from the examiner

should be directed to David Nhu, (571)272-1792. The examiner can normally be reached

on Monday-Friday from 7:30 AM to 5:00 PM.

The examiner's supervisor, David Nelms can be reached on (571)272-1787.

The fax phone number for the organization where this application or proceeding is assigned is

(703)872-9306.

Any inquiry of a general nature or relating to the status of this application or proceeding should

be directed to the receptionist whose telephone number is (703) 308-0956

David Nhu 🌬

November 9, 2004

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